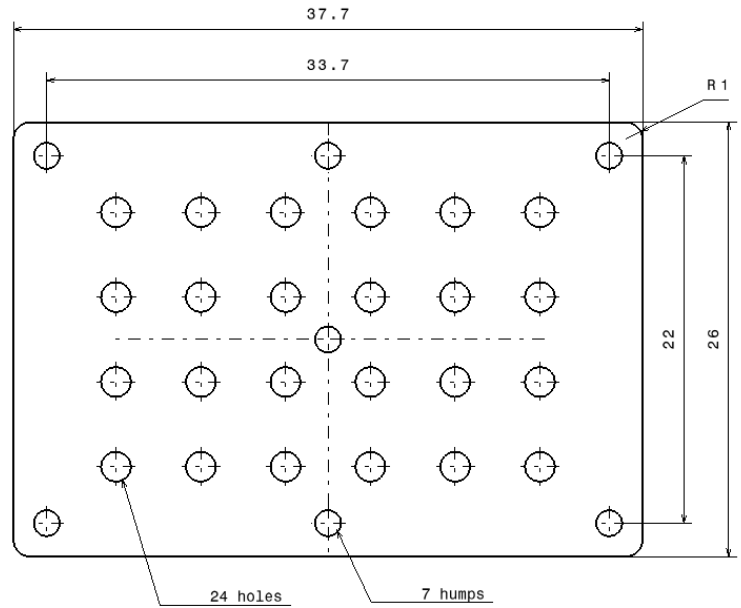
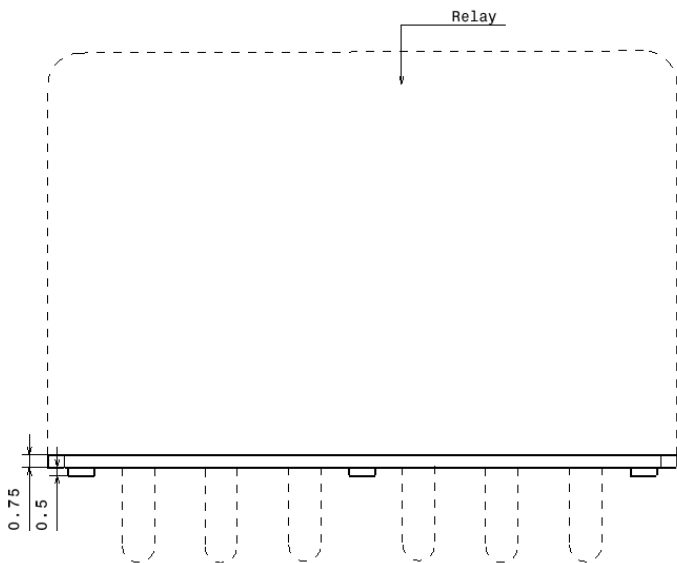




DESIGNED FOR RELAY SERIES:

F600, F601
 F670, FD670



- Dimensions are in mm
- Isolation pad is fitted with humps to be positioned on the PCB side. These humps allow the cleaning of the solder Flux.
- Humps diameter : 1.57mm – Humps Height : 0.5mm
- Typical Pitch of Holes for the relay pins : 5.08mm

GENERAL CHARACTERISTICS
 CARACTERISTIQUES GENERALES

Material <i>Matière</i>	Pocan PBT-GF30
Weight <i>Poids</i>	1.15g max
Maximum temperature <i>Température maximum</i>	244°C
Flammability rating UL 94 <i>Indice d'inflammabilité UL 94</i>	V-0

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The technical information provided by Leach International Europe is to be used as a guide only, and is not meant for publication or as documentation for altering any existing specification. Dimensions are in millimeters unless otherwise specified. Rev. 03/2025